



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of)
Masanori MINAMIO et al.) Group Art Unit: 2827
Serial No. 10/083,311) Examiner: Lourdes C. CRUZ
Filed: February 27, 2002)
For: LEAD FRAME)

CERTIFICATE OF MAILING

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Deborah A. Zonne

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Official Action dated October 7, 2002, please amend the above-identified application as follows.

IN THE CLAIMS:

Please amend claim 1 as follows:

1. (Amended) A lead frame, comprising:
 - a frame body made of a conductive material and including at least one opening for mounting a semiconductor chip;
 - a die pad placed in the opening of the frame body; and
 - a group of leads extending from the frame body into the opening, the group of leads including at least:
 - a first lead connected to the frame body and including a first bonding pad provided on an upper surface of the first lead and a first land provided on a lower surface of the first lead;
 - a second lead directly connected to the frame body and including a second bonding pad provided on an upper surface of the second lead and a second land provided on a lower surface of the second lead; and
 - a third lead connected to the first lead and including a third bonding pad provided on an upper surface of the third lead and a third land provided on a lower surface of the third lead,

wherein an array of the second bonding pad is between an array of the first bonding pad and an array of the third bonding pad,

wherein a connecting portion that is thinner than the lead frame body and that can be punched through is provided between the first lead and the third lead.